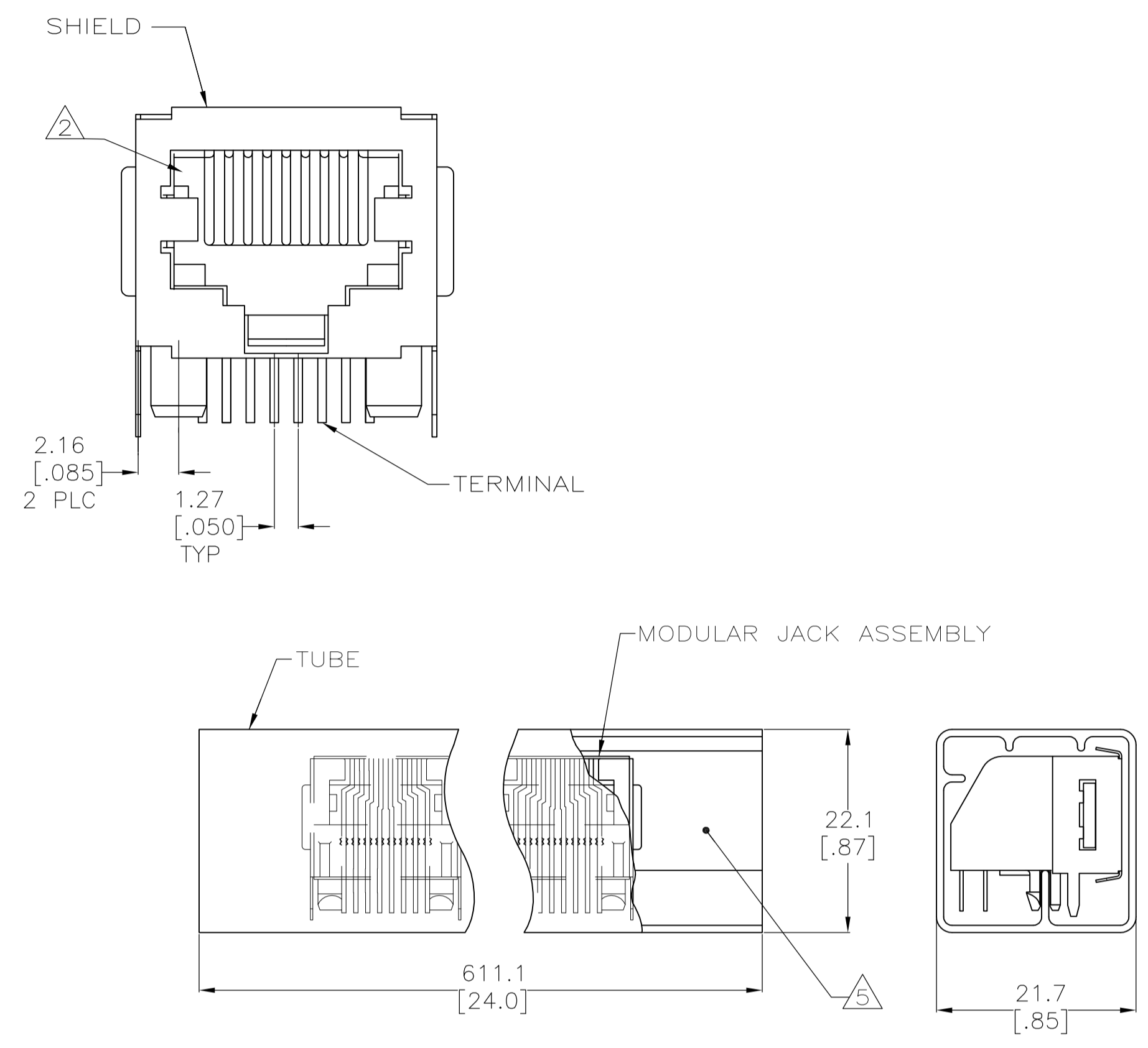
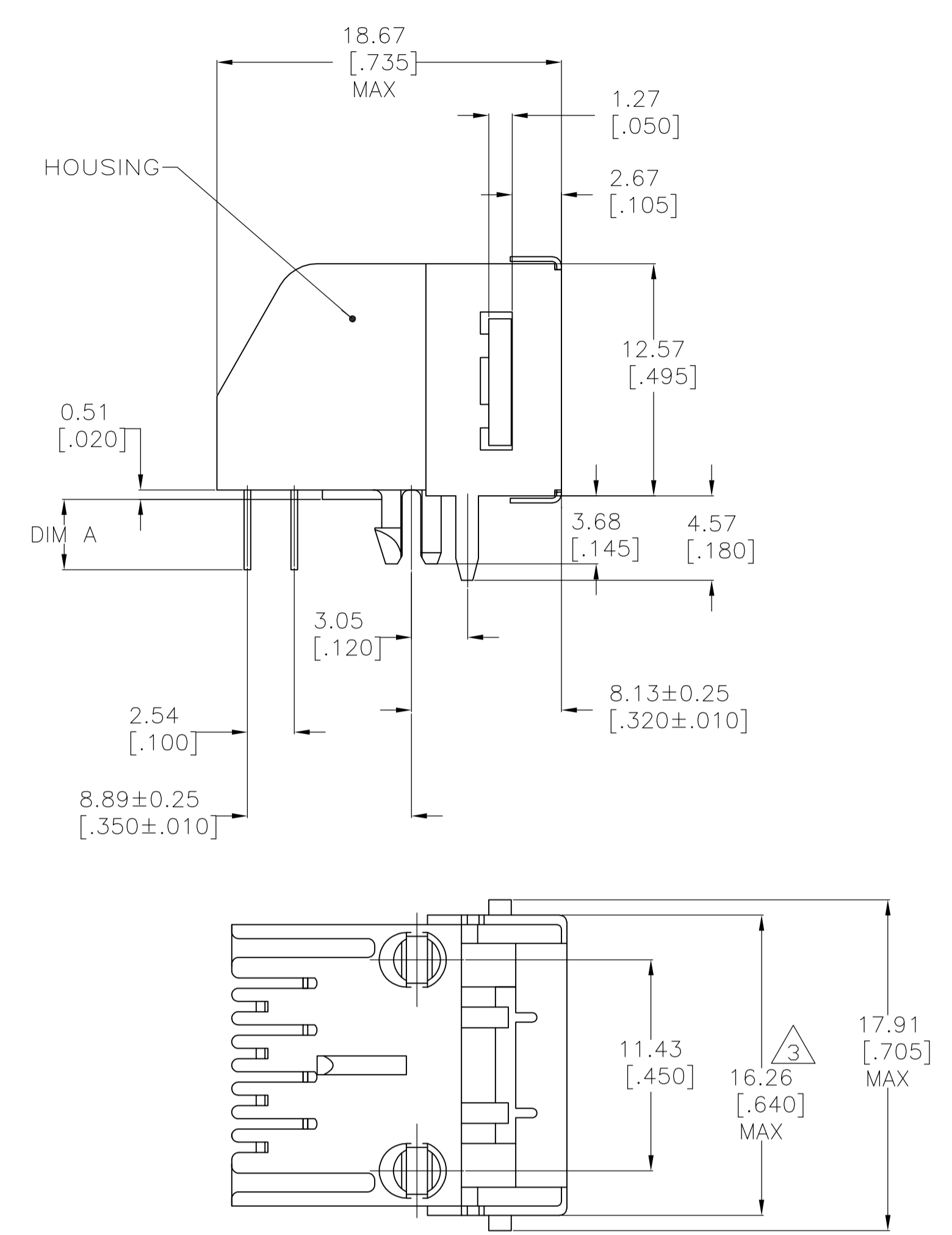
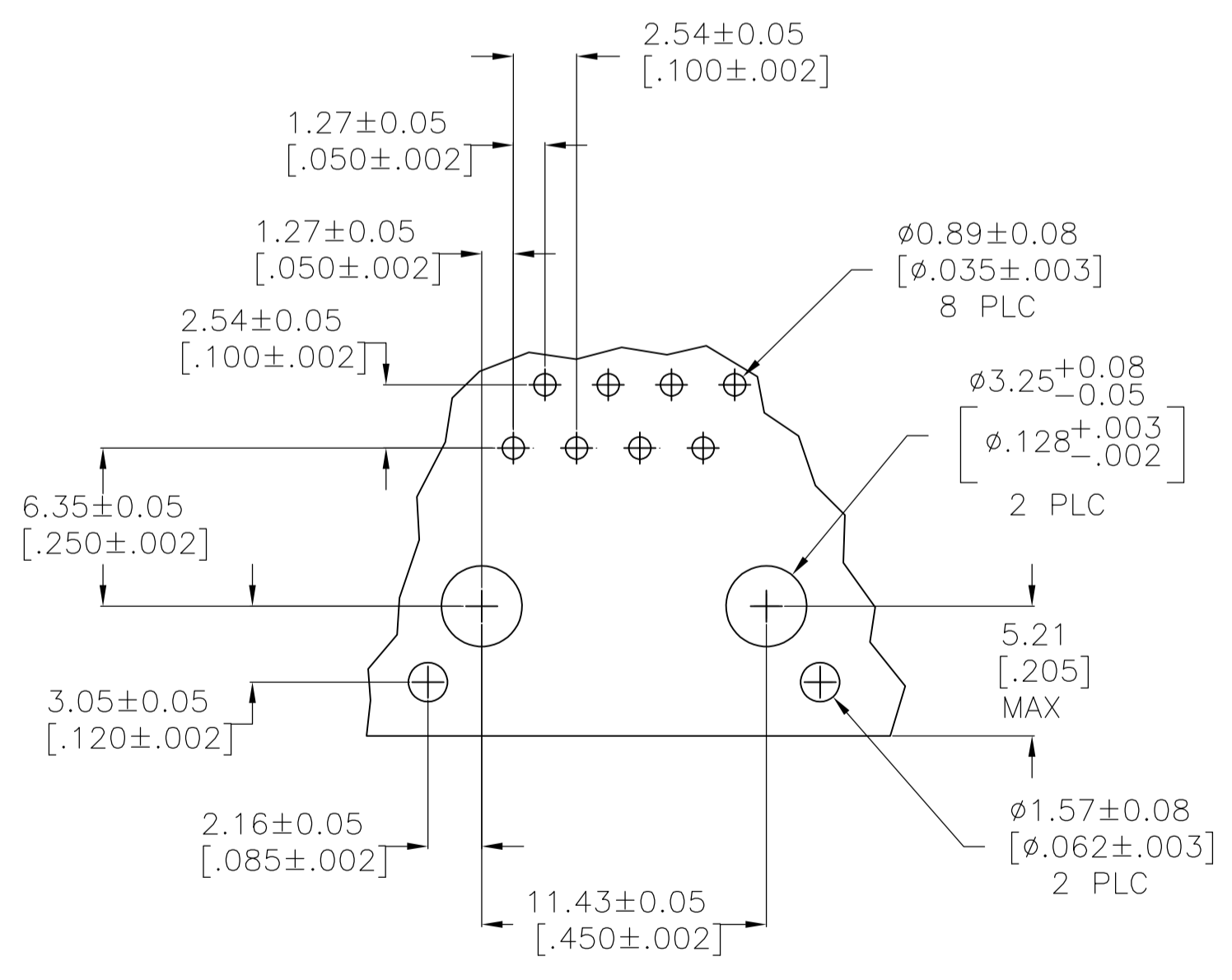


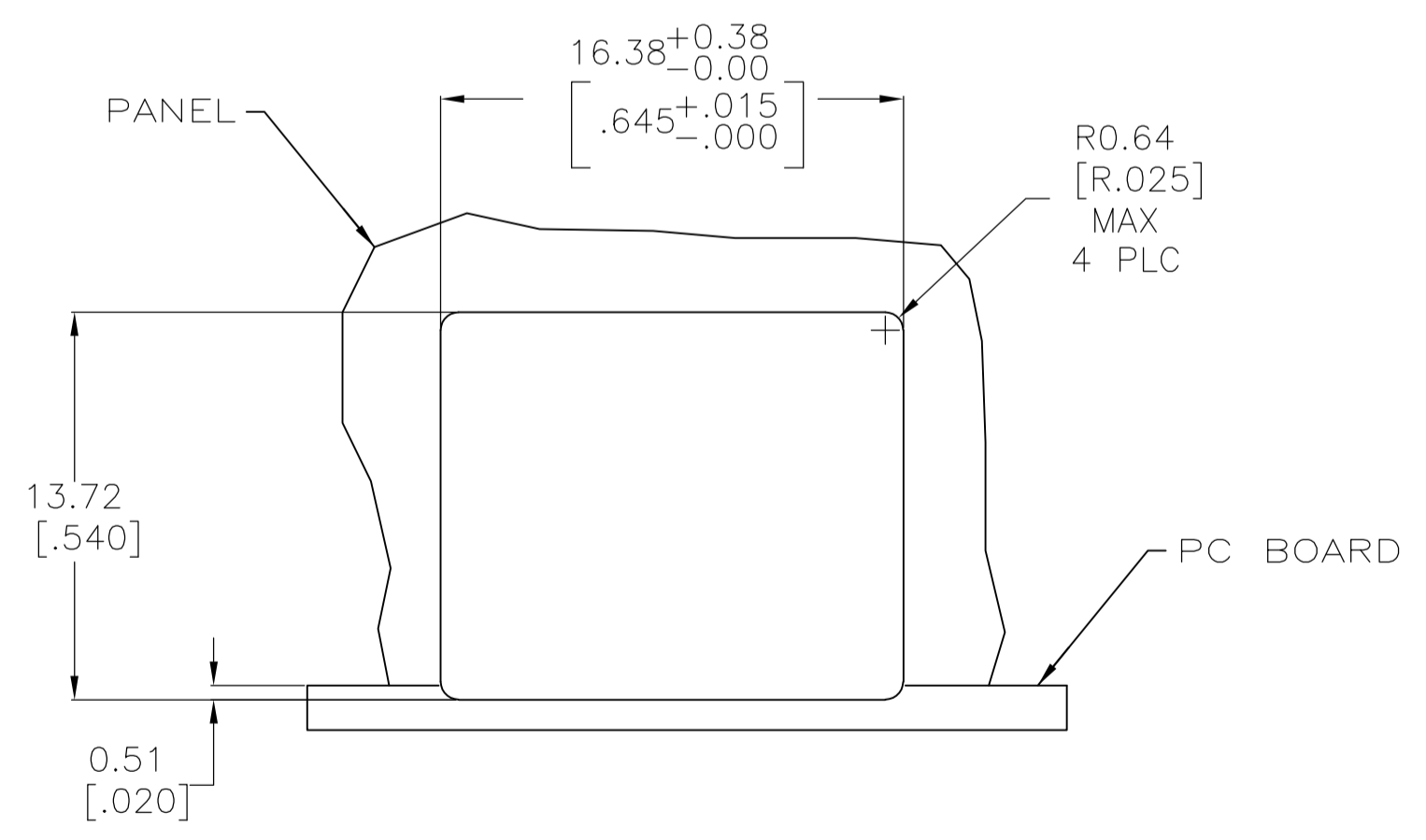
LOC		DIST		REVISIONS			
GP	00	REV	DATE	BY	CHK	APPV	
D1	REVISED PER ECO-11-005140		28MAR11	RK	HMR		



DETAIL B
SCALE 2:1



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)



RECOMMENDED PANEL CUTOUT

1. MATERIAL:
 HOUSING - PBT POLYESTER, COLOR: BLACK
 TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27 μ m [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03 μ m [.000080] THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m [.000050] THICK NICKEL UNDERPLATE
 SHIELD - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 3.0 μ m [.000120] MINIMUM THICK REFLOWED TIN
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
 - 3 DIMENSIONS MEASURED ALONG FRONT EDGES OF MATING FACE
 - 4 BULK PACKAGED IN A TRAY
 - 5 32 ASSEMBLIES PACKAGED PER TUBE. SEE DETAIL B

1.78-2.79 [.09±.02]	4	5555153-6
2.54-3.05 [.11±.01]	4	5555153-5
3.30-4.32 [.15±.02]	5	5555153-3
3.30-4.32 [.15±.02]	4	5555153-1
DIM A	PACKAGED	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± - 2 PLC ± 0.13[.005] 3 PLC ± - 4 PLC ± - ANGLES ± -	APPROVED: S. FLICKINGER DATE: 05NOV2007	NAME: MODULAR JACK ASSEMBLY, SHIELDED, 8 POSITION, LOW PROFILE, RIGHT ANGLE, PANEL GROUND WITH PANEL STOPS
MATERIAL: SEE NOTE 1	FINISH: SEE NOTE 1	WEIGHT: -	RESTRICTED TO: -

STE TE Connectivity

CUSTOMER DRAWING SCALE 4:1 SHEET 1 OF 1 REV D1